

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-15. (Canceled)

16. (New) Microcomponent comprising a hermetically-sealed microcavity, delineated by a cover in which at least one hole is formed, and, on the cover, a sealing layer hermetically sealing the microcavity, the microcomponent comprising, under the sealing layer, a plug covering the hole and a part of the cover over the periphery of the hole, the sealing layer and the plug being formed by distinct materials, wherein the plug is made of a material that is able to undergo creep deformation.

17. (New) Microcomponent according to claim 16, wherein the material that is able to undergo creep deformation is a polymerized material.

18. (New) Microcomponent according to claim 17, wherein the polymerized material is selected from photoresists and polyimide.

19. (New) Microcomponent according to claim 16, wherein the material that is able to undergo creep deformation is a glass.

20. (New) Microcomponent according to claim 19, wherein the glass is selected from phosphosilicate glasses.

21. (New) Microcomponent according to claim 16, wherein the dimension of the hole is smaller than 5 micrometers.

22. (New) Microcomponent according to claim 16, wherein the hole is arranged on the highest part of the microcavity.

23. (New) Microcomponent according to claim 16, comprising a plurality of holes.

24. (New) Microcomponent according to claim 16, wherein the thickness of the plug is comprised between 2 and 6 micrometers.

25. (New) Microcomponent according to claim 16, wherein the plug comprises sloping sides.

26. (New) Microcomponent according to claim 16, wherein the plug is non-hermetical.

27. (New) Microcomponent according to claim 16, wherein the material of the sealing layer is selected from silicon dioxide, silicon nitride and metals.

28. (New) Method for production of a hermetically-sealed microcavity of a microcomponent according to claim 16, successively comprising

- deposition of a sacrificial layer on a substrate,
- deposition of a first layer forming the cover, on the substrate and sacrificial layer,

- etching, in the cover, of at least one hole opening out onto the sacrificial layer,
- removal of the sacrificial layer, via the hole, so as to create the microcavity,
- deposition of the sealing layer, so as to seal the microcavity hermetically,

method comprising deposition of the plug covering the hole and a part of the cover over the periphery of the hole, after the sacrificial layer has been removed and before the sealing layer is deposited.

29. (New) Method according to claim 28, wherein, the plug is made of phosphosilicate glass, and the plug is obtained by a method selected from solgel methods and cathode sputtering.

30. (New) Method according to claim 28, wherein the plug is made of a porous material.

31. (New) Method according to claim 30, wherein, the porous material is a photoresist, and the method comprises a high temperature annealing step.

32. (New) Method according to claim 30, wherein the method comprises a pumping step of the gas contained in the microcavity, through the porous material, before the sealing layer is deposited.